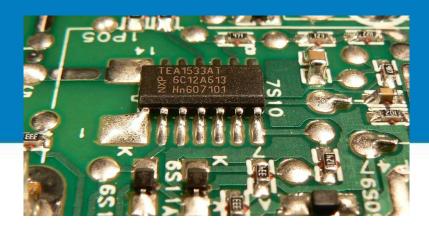


ALPHA® SACX[™] Plus 0107 Product Information







Overview

- ALPHA SACX[™]Plus 0107 is a new wave solder alloy based on the very successful ALPHA SACX[™] platform
- The alloy is designed to offer low cost high performance for FR2 and simple FR4 boards.
- The product has been formulated to deliver high reliability and excellent wetting.



Formulation Highlights

- Process Yield: A fast wetting speed and high wetting force is achieved by selecting combination of elements to optimise the wetting performance of the alloy while keeping material costs as low as possible.
- Hole Fill: Formulated to deliver Superior Hole fill to Sn/Cu (Ni or Co) alloys.
- Bridging Performance: Specific addition of elements improve the bridging performance compared to Sn/Cu (Ni or Co) alloys
- Copper Dissolution Rate: Additives to the alloy reduce the copper dissolution rate.
- Dross Rates: The successful anti-oxidant technology used in SACX0307 has been incorporated into SACX™ Plus 0107.
- Value: Delivers greater value than any competitive product.

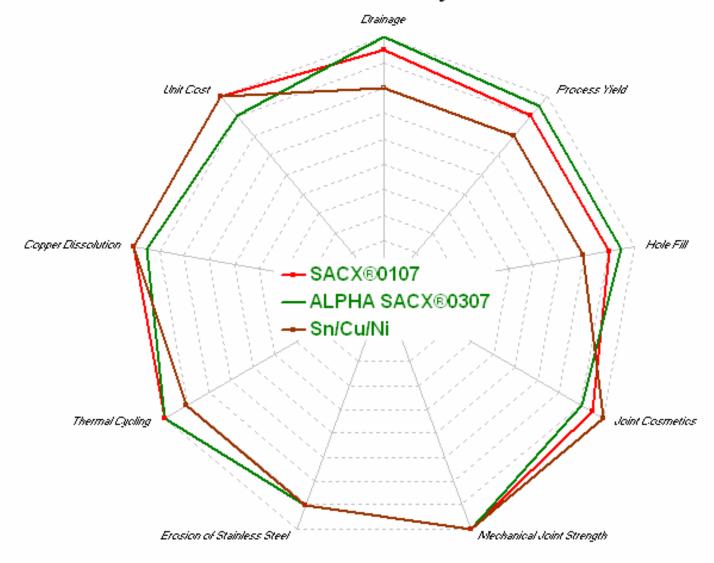


SACX[™] Plus 0107 Data Table

SACX [™] Plus 0107 Data table			
Characteristic	SACX [®] 0107	Units	
Liquidus	228	°C	
Solidus	217	°C	
Wetting Time To (EF-8000 Flux)	1.10	Sec	
Wetting Force Max	6.09	mN	
Density	7.40	g/cc	
Process Yield data (PCV Phase)	38	Defects	
Drossing Levels	13.36	g/hr	
Tensile - Max stress at break	31.3	MPa	
Tensile - Elongation % at break	17%	%	
Hardness - As cast	21.98	Hv2.5	
Hardness - aged 125°C for 24 hours	17.89	Hv2.5	



PbFree Wave Solder Alloy Attribute Balance

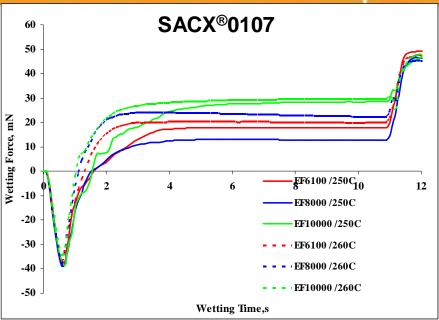


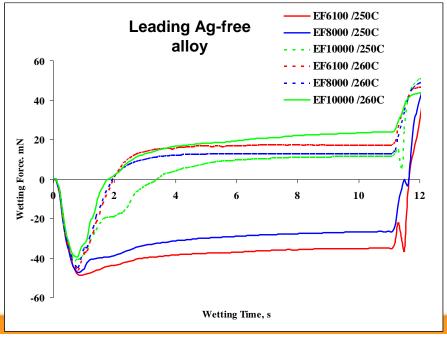


- SACX[™] Plus 0107
 delivers very fast wetting
 speed and highest
 wetting force
- This superior performance is maintained with different flux chemistries.
- High wetting forces are robust at the lower operating temperature of 250C

Test considerations:

- 3 Flux Types
- 2 Temperatures

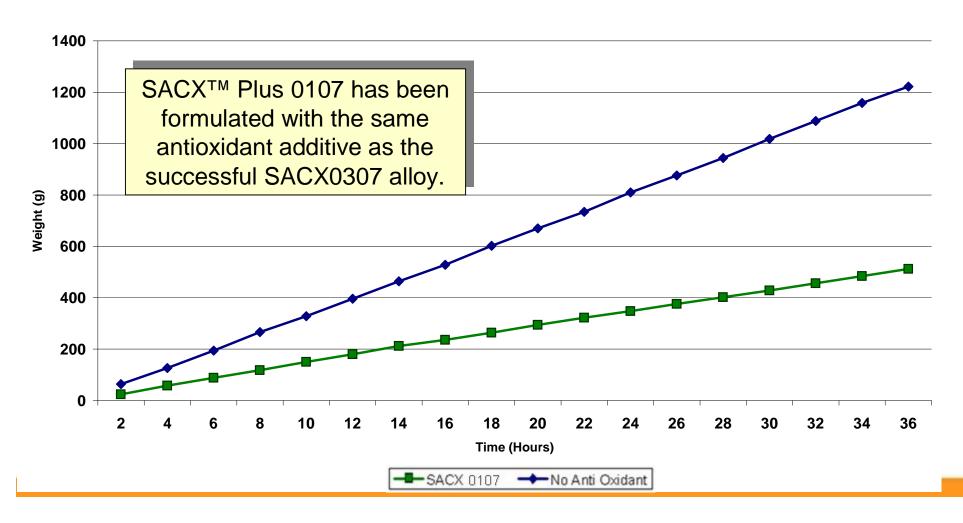




SACXTM Plus 0107 Oxidation Results

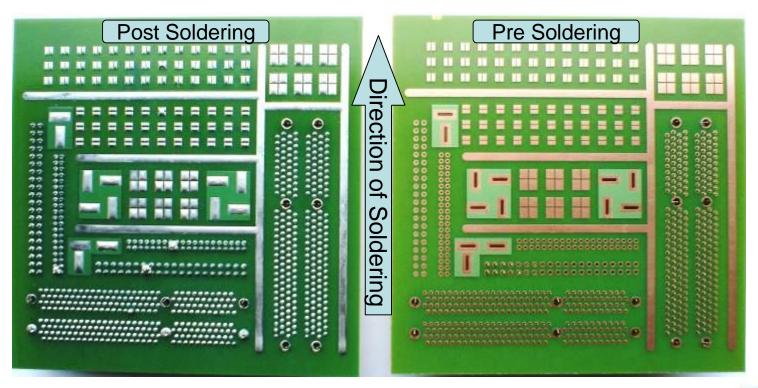
SACX™ Plus 0107

Dross Levels Comparison



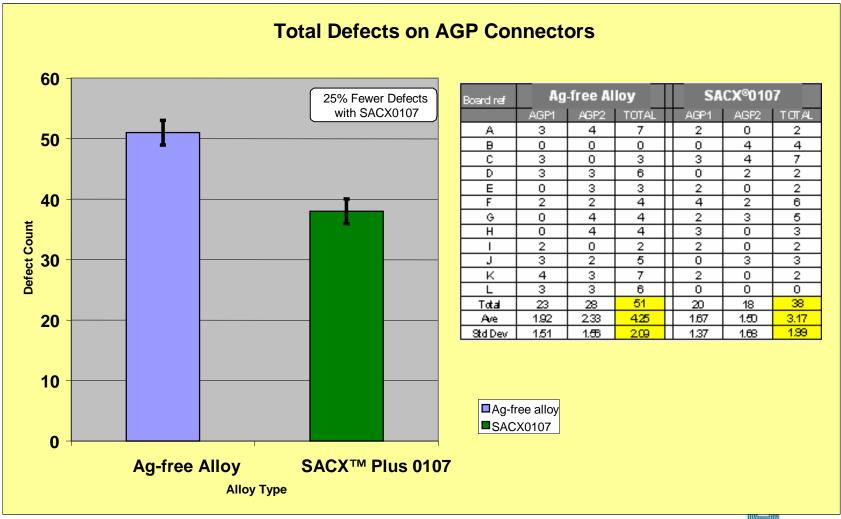
Process Yield Data

- Test Board FR2 OSP and Rosin pad finishes.
- 4 AGP connectors, 4 headers





Process Yield data

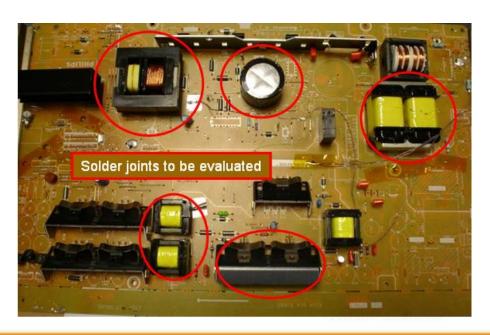


Reliability Data

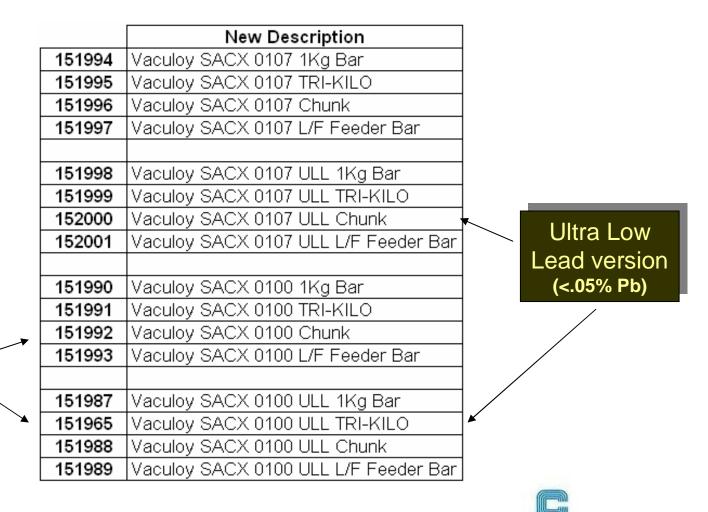
- Test board : FR2 TV board (LCD TV) with large, high thermal mass power management devices.
- Cycle profile:
 - 1000 x 2 hour cycles
 - -20°C to +85°C
 - Dwell at upper and lower temperature 45minutes to alloy full stress relief of solder joints

Results:

- After 500 cycles, no sign of damage could be seen on the SACX[™] Plus 0107 boards.
- After 1000 cycles ... SACX[™] Plus 0107 faired the best (of all the alloys tested) with some cracking to two components, and signs of damage to only one other component.



Available Globally



Cu free replenishment alloy

Cookson Electronics